

U.S. Department of Commerce, Patent and Trademark Office

(PTO Form 1449 modified)

Docket No.

AMAT/4180/DSM/BC
VD/JW

Serial No.

09/902,518

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Applicant

Huang, et al.

Confirmation No.:

7428

(Use several sheets if necessary)

Filing Date

July 10, 2001

Group





2824

Examiner M. S. Lebentritt

U.S. Patent Documents

*Examiner Initial		Document Number	Issue Date	Applicant(s) Name	Class	Subclass	Filing Date If Appropriate
<i>MSL</i>	A1	6,537,733 B2	03/25/2003	Campana, et al	430	313	02/23/2001
<i>MSL</i>	A2	6,486,042 B2	11/26/2002	Gehrke, et al	438	462	07/16/2001
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<i>MSL</i>	A5	5,869,147	02/09/1999	Konig	427	537	04/01/1995
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Foreign Patent Documents							

Foreign Patent Documents

*Examiner Initial		Document Number	Date	Country	Class	Subclass	Translation	
							YES	NO
	B1	EP 0 785 475 A2	07/23/1997	Europe	G03G	5/082	<input checked="" type="checkbox"/>	<input type="checkbox"/>
	B2	EP 0 194 652	09/17/1986	Europe	C23C	14/06	<input checked="" type="checkbox"/>	<input type="checkbox"/>
	B3	DE 39 07 857 C1	05/23/1990	Germany	C23C	16/32	<input type="checkbox"/>	<input checked="" type="checkbox"/>
	B4	DE 19654737A1	07/03/1997	Germany			<input type="checkbox"/>	<input checked="" type="checkbox"/>
OTHER ART							<input type="checkbox"/>	<input checked="" type="checkbox"/>

OTHER ART

*Examiner Initial	Including Author, Title, Date, Pertinent Pages, Etc.
<i>MSL</i>	C1 Youngsoo P., et al., Institute of Electrical Engineers, "Endothermic reactions between mullite and silicon carbide in an argon plasma environment," Journal of American Ceramic Society, USA, Jan. 1988, American Ceramic Soc., USA, Vol. 81, No 1, pp. 233-236, XP-002201865.
<i>MSL</i>	C2 Tremblay, Marc, et al., "Hexagonal Sensor with Imbedded Analog Image Processing for Pattern Recognition," Custom Integrated Circuits Conference, May 9, 1993, pp. 12701-12704, XP-000409694.
<i>MSL</i>	C3 Partial European Search Report from EP 00 10 9917, dated July 3, 2002.

Examiner*

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.

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							YES	NO
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OTHER ART

*Examiner Initial		Including Author, Title, Date, Pertinent Pages, Etc.
<i>ML</i>	C4	U.S. Patent Application, Serial Number: 09/657,392, Filing Date: September 8, 2000.
<i>ML</i>	C5	U.S. Patent Application, Serial Number: 09/627,667, Filing Date: July 28, 2000.
<i>ML</i>	C6	U.S. Patent Application, Serial Number: 09/336,525, Filing Date: June 18, 1999.
Examiner <i>[Signature]</i>	Date Considered <i>[Signature]</i>	

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